

HEADER FOR SURFACE MOUNT BETWEEN PARALLEL CIRCUIT BOARDS

ABSTRACT OF THE DISCLOSURE

A header includes a substrate made of an insulative material that has a plurality of through holes formed therein extending between upper and lower sides of the substrate. Plating is applied to the through holes to form conductive cylinders with upper and lower ends. A plurality of solder balls are attached to corresponding upper and lower ends of the conductive cylinders. A pair of circuit boards can be mechanically and electrically interconnected with the solder ball header in spaced apart parallel relationship. The solder balls bond the ends of the conductive cylinders with opposing conductive traces or pads formed on the circuit boards.

Patent No. 0554007